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The applied current densities were wrongly calculated. The revised Fig. 3 with correct current densities is shown below. In addition, the value of “9.2 × 10^4 A/cm^2” in the abstract, on p. 152105, and in figure caption of Fig. 2 should be modified as “9.7 × 10^3 A/cm^2.” The value of “5 × 10^4 A/cm^2” on p. 152105 should be revised as “5.3 × 10^3 A/cm^2.” These corrections do not affect any other part of the article and the conclusions.

![Diagram of measured temperature increase in the bump as a function of current and current densities.]

FIG. 3. The measured temperature increases in the bump as a function of applied current and current densities.

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